

AMENDMENT TO CLAIMS

In the Claims

Please AMEND claims 1, 5, 11 and 13 as noted below.

Please cancel claims 3, 7, 9, 10, 12, and 14 without prejudice or disclaimer.

A copy of all pending claims and a status of the claims are provided below.

1. (Currently Amended) A method for manufacturing a thin flat panel display, the method comprising:

preparing an etchable upper substrate and an etchable lower substrate;

forming image display devices on an inner surface of the lower substrate in such a way that the at least two image display devices are isolated from each other;

combining the upper substrate and the lower substrate together so that the image display devices are ~~individually sealed up~~ each surrounded by an inner sealant having no plugged openings therein;

etching outer surfaces of the upper substrate and the lower substrate; and

cutting the combined upper and lower substrates in units of an image display device such that each image display device is separate,

~~wherein each of the image display devices are surrounded by an inner sealant and all of the image display devices and the inner sealant are surrounded by an outer sealant,~~

wherein the combining comprises attaching an unetchable protection film to each lateral side of the combined upper and lower substrates, and

wherein the image display devices are organic EL display devices.

2. (Original) The method of claim 1, wherein the upper and lower substrates are formed of a glass-based material.

3. (Canceled)

4. (Previously Presented) The method of claim 1, wherein during the etching, the outer surfaces of the upper and lower substrates are etched so that the upper substrate and the lower substrate each have a total thickness of at most 0.5mm.

5. (Currently Amended) A method for manufacturing a thin flat panel display, the method comprising:

preparing an etchable upper substrate and an etchable lower substrate;

forming an image display device on an inner surface of the lower substrate;

combining the upper substrate and the lower substrate together so that the image display device is ~~sealed up~~ surrounded by an inner sealant having no plugged openings therein; and

etching outer surfaces of the upper substrate and the lower substrate,

~~wherein each of the image display devices are surrounded by an inner sealant and all of the image display device[[s]] and the inner sealant are surrounded by an outer sealant,~~

wherein the combining comprises attaching an unetchable protection film to all of each lateral side of the combined upper and lower substrates, and

wherein the image display device is an organic EL display device.

6. (Original) The method of claim 5, wherein the upper substrate and the lower substrate are formed of a glass-based material.

7. (Canceled)

8. (Previously Presented) The method of claim 5, wherein during the etching step, the outer surfaces of the upper substrate and the lower substrate are etched so that the upper and lower substrates each have a total thickness of at most 0.5mm.

9. (Canceled)

10. (Canceled)

11. (Currently Amended) The method ~~according to~~ of claim 1, wherein the inner sealant completely surrounds ~~each of~~ the image[[d]] display device[[s]].

12. (Canceled)

13. (Currently Amended) The method ~~according to~~ of claim 5, wherein the inner sealant completely surrounds ~~each of~~ the image[[d]] display device[[s]].

14. (Canceled)